ABSTRACT

WAFER-RETAINING ELASTIC FILM OF CMP DEVICE

A wafer-retaining elastic film (10) of a CMP device includes: a film body (11) comprised of an elastic material; and a coating layer (12) formed so as to cover the surface on the wafer retaining side of the film body (11). The coating layer (12) contains a polymeric binder and nonmetallic particles dispersed in the polymeric binder.